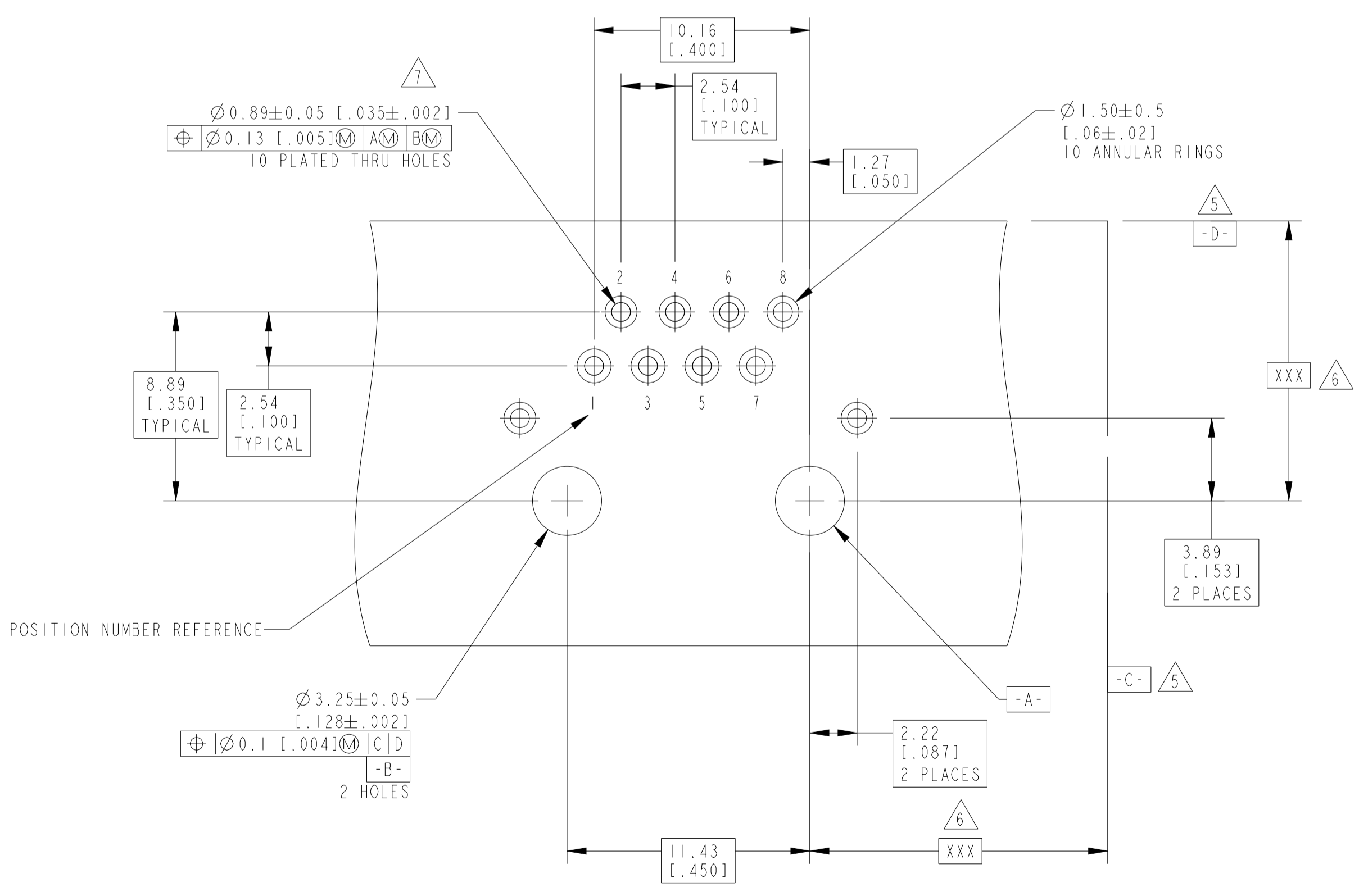
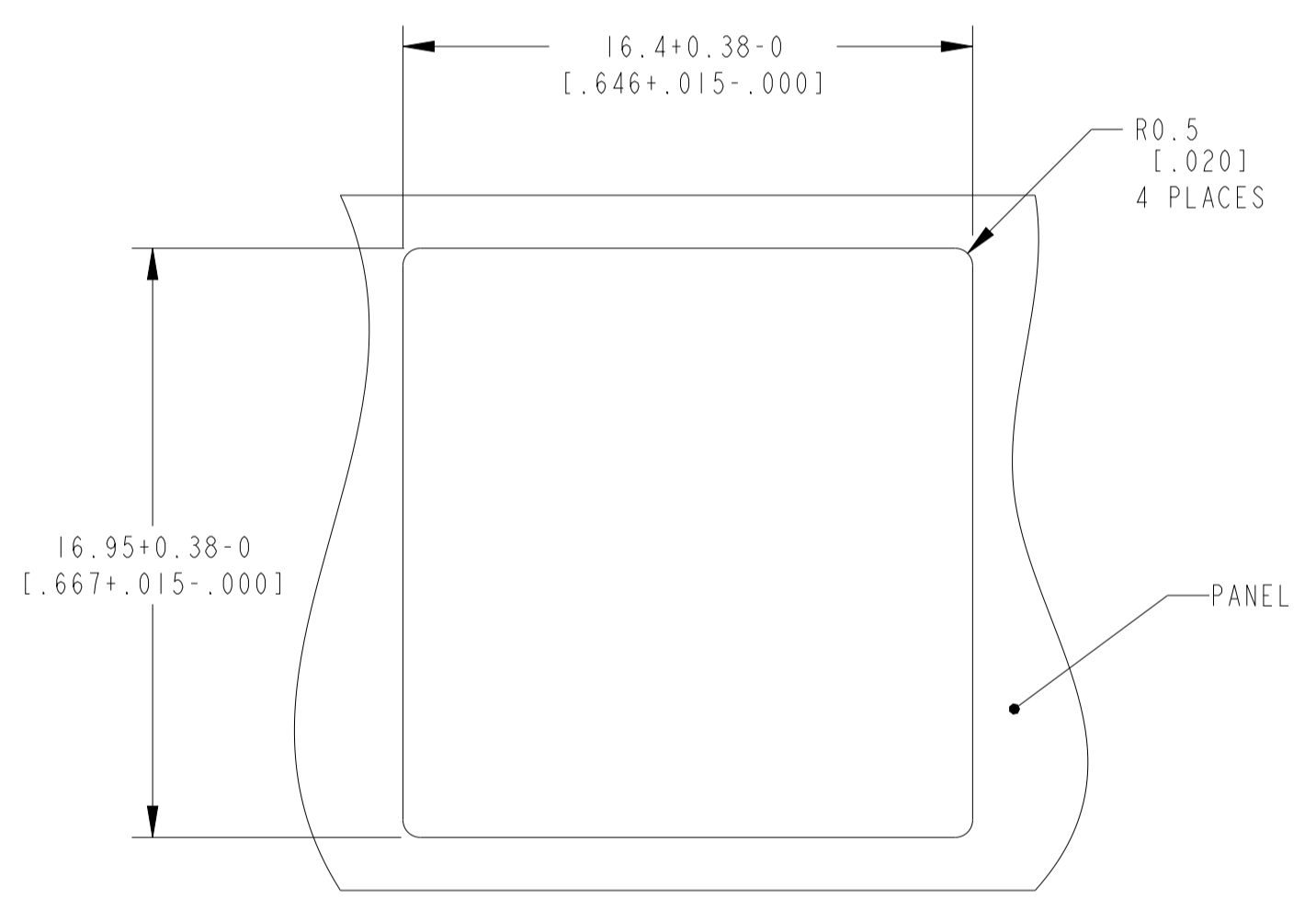
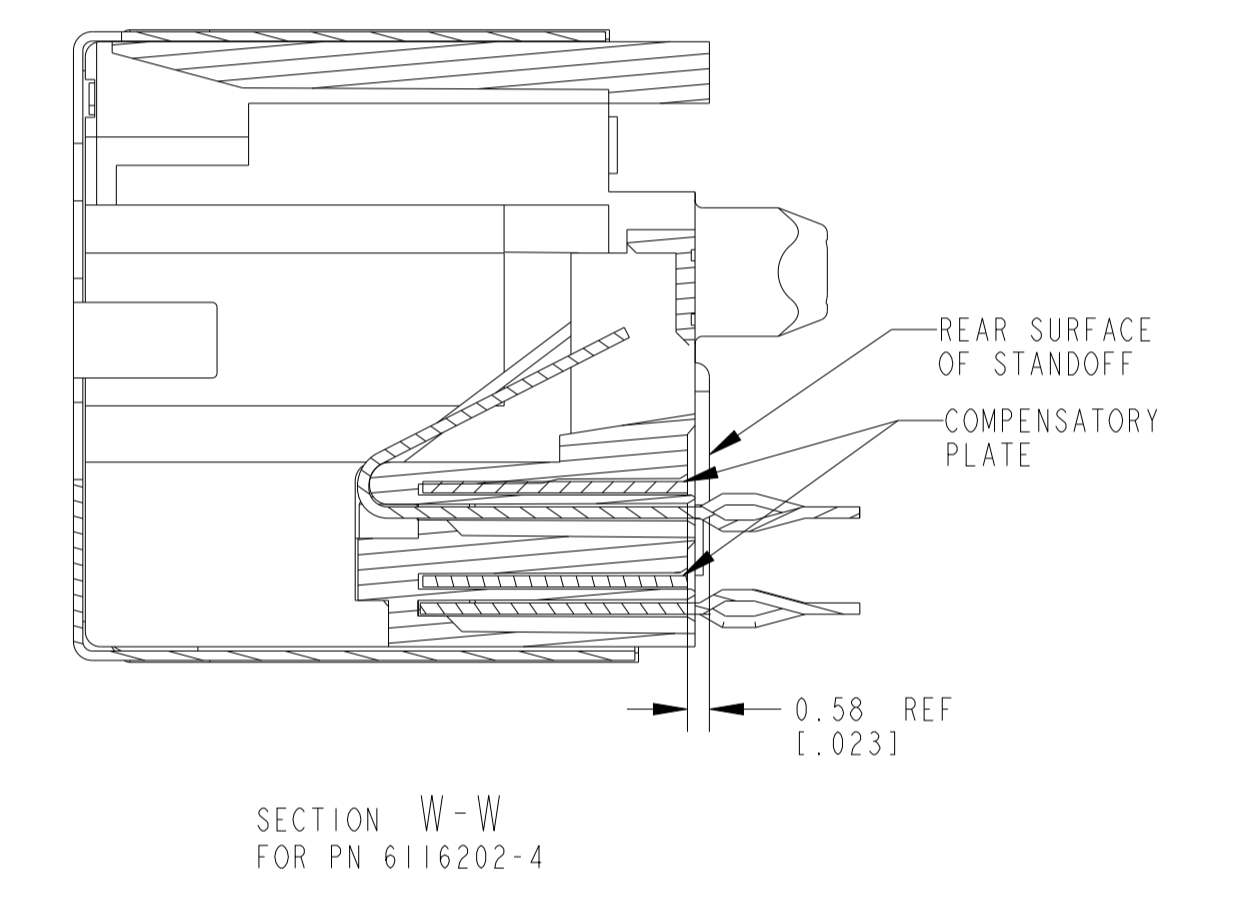
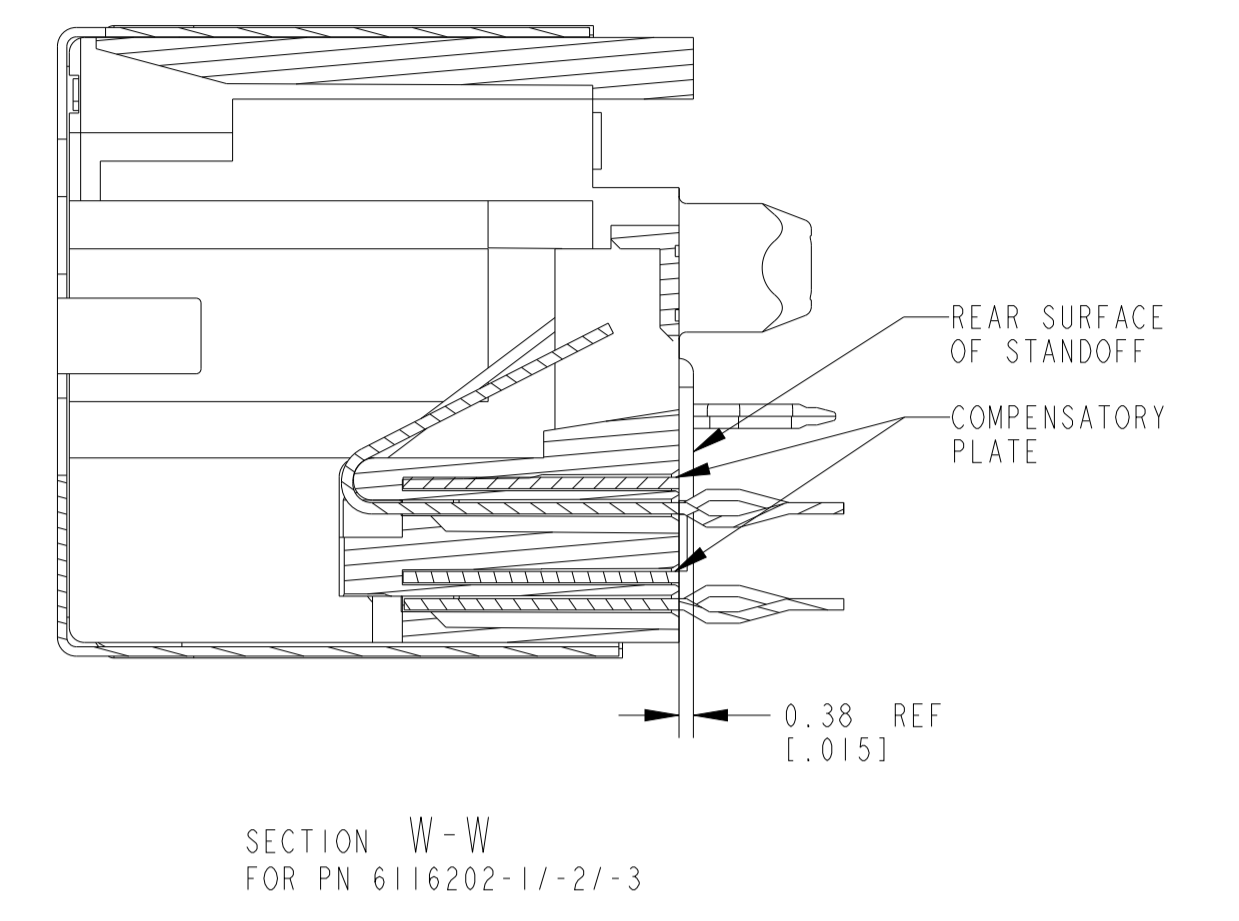
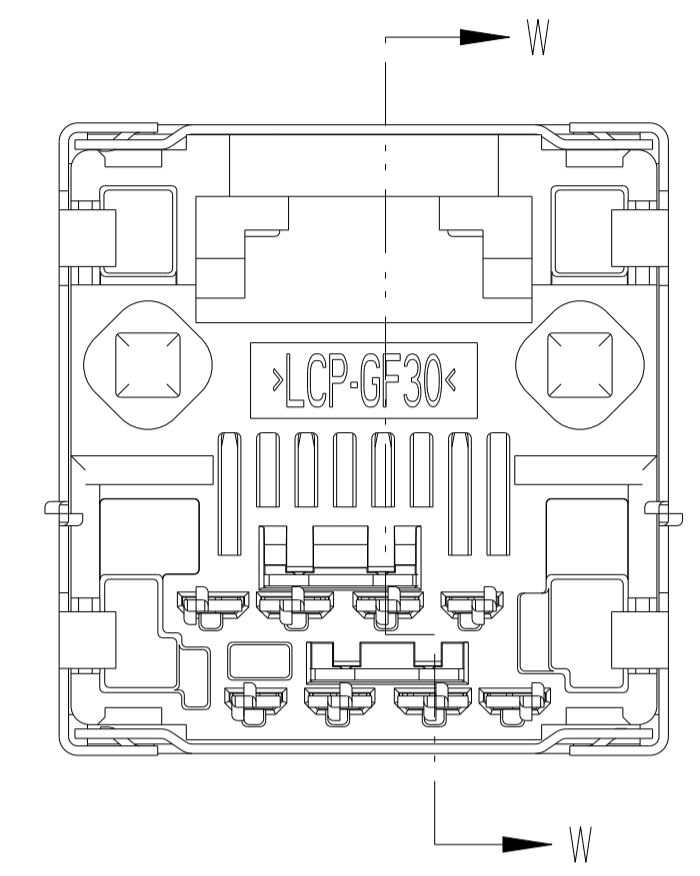
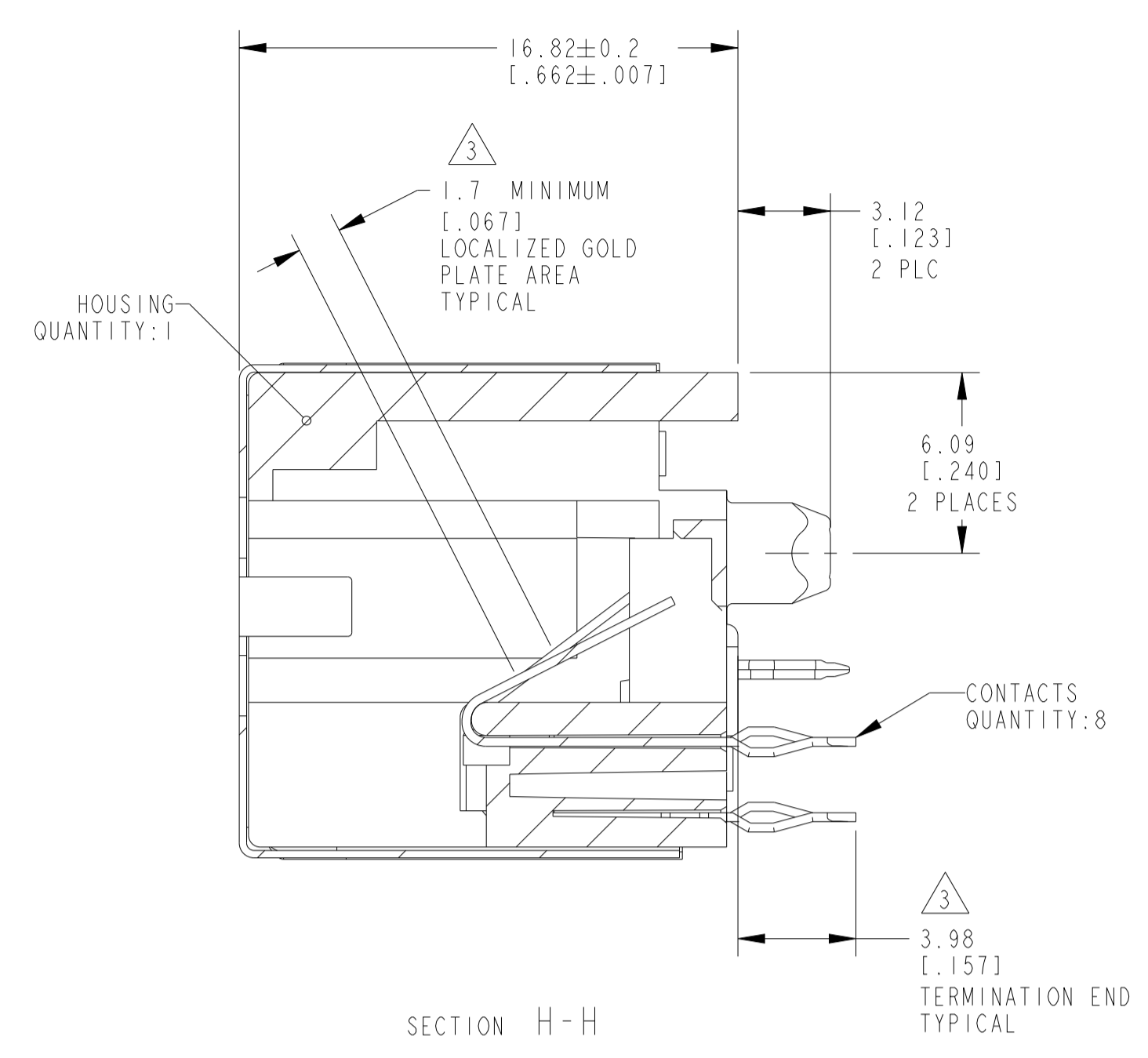
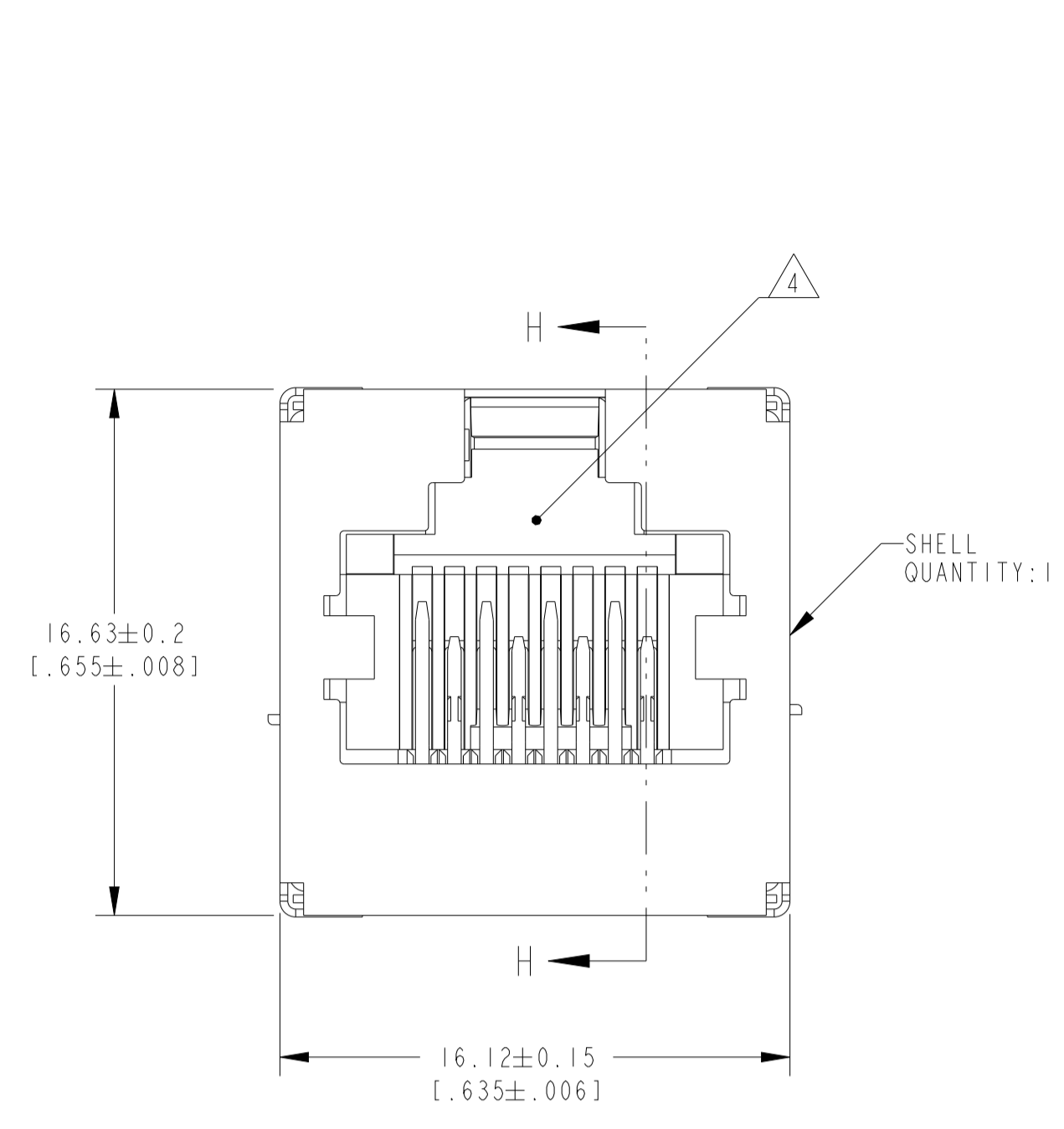
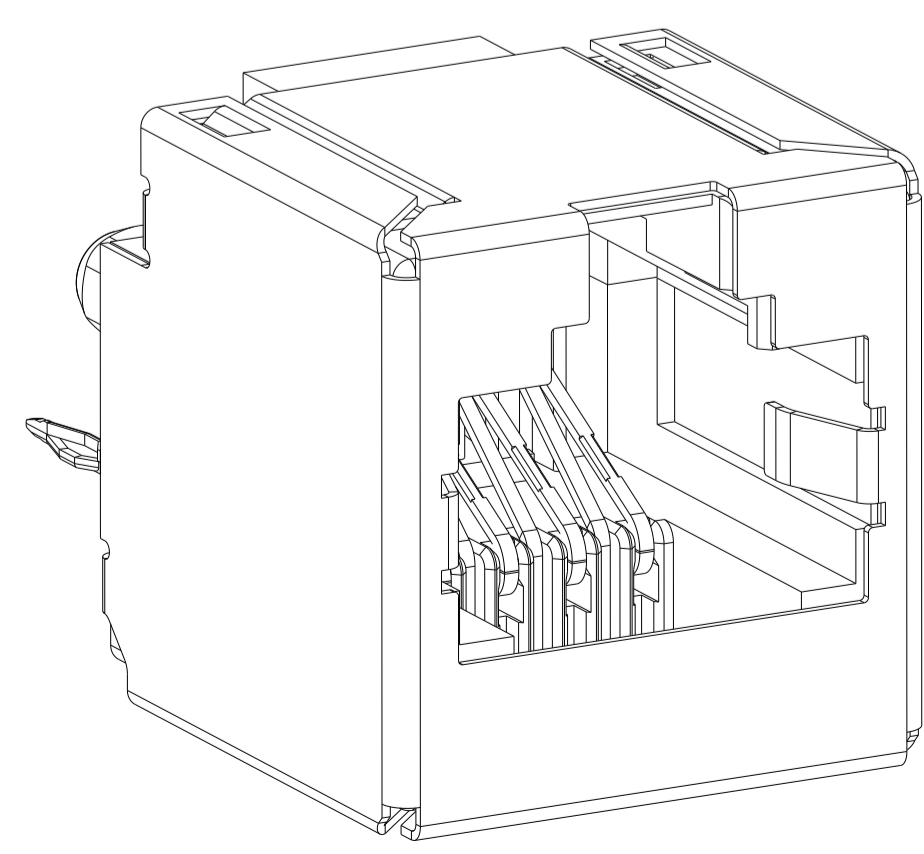


LOC	DIST	REVISIONS					
		P	LTN	DESCRIPTION	DATE	DMN	APVD
AA	22	D3		REVISED PER ECO-11-005033	18MAR2011	RK	HMR
		E		ECO-11-019083	22SEP2011	JJ	MOW
		E1		REVISED PER ECR-23-166294	13APR2023	IT	WH



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
 RECOMMENDED PRINTED CIRCUIT BOARD THICKNESS 1.4 [0.055] MIN
 COMPONENT SIDE OF PRINTED CIRCUIT BOARD



- 1 THERMOPLASTIC.
- 2 PHOSPHOR BRONZE
- 3 1.27 μ m [0.000050] MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2 μ m [0.000079] MIN MATTE TIN ON TERMINATION END, BOTH OVER 1.27 μ m [0.000050] MIN NICKEL.
- 4 CAVITY CONFORMS TO FCC 47 CFR 68 PART F.
- 5 DATUMS ESTABLISHED BY CUSTOMER.
- 6 DIMENSIONS ESTABLISHED BY CUSTOMER.
- 7 DRILLED HOLE DIAMETER 1.02±0.03 [0.040±0.001]. COPPER THK 0.03-0.08 [0.001-0.003]. TIN THICKNESS 8 μ m [0.000315] MIN.
- 8 COPPER ZINC ALLOY
- 9 OUTER SHELL PLATED WITH 1.27 μ m MIN NICKEL.
- 10 PC BOARDS GREATER THAN 1.57 [0.062] IN THICKNESS MAY REQUIRE SPECIAL EXTRACTION TOOLING, CONSULT ENGINEERING.
- 11 PACKAGED 29 PIECES PER TUBE
- 12 PACKAGED 27 PIECES PER TUBE
- 13 WITH IMPROVED CHAMFERS ON TERMINAL EDGES.
- 14 WITHOUT COMPENSATORY PLATE

PACKAGING	COLOR	PART NUMBER
11, 13, 14	NATURAL	6116202-6
12, 13	NATURAL	6116202-5
11	BLACK	6116202-4
12	NATURAL	6116202-3
11	NATURAL	6116202-2
11	BLACK	6116202-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DMN	L.A.MAYER	20APR2005
CHK	J.WESTMAN	20APR2005
APVD	S.FELCKINGER	20APR2005

NAME: MODULAR JACK ASSEMBLY, VERTICAL, COMPLIANT PIN, SHIELDED, 8 POSITION, CATEGORY 5

PRODUCT SPEC: 108-1163-6

APPLICATION SPEC: 114-2158

WEIGHT: -

CUSTOMER DRAWING

SCALE: 5:1

SHEET 1 OF 1

REV E